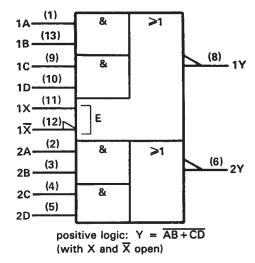
- Package Options Include Plastic and Ceramic DIPs and Ceramic Flat Packages
- Dependable Texas Instruments Quality and Reliability

description

These devices contain two independent 2-wide 2-input AND-OR-INVERT gates with one gate expandable. They perform the Boolean function $Y = \overline{AB + CD}$ with X and \overline{X} left open.

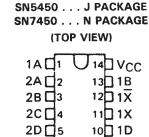
The SN5450 is characterized for operation over the full military temperature range of $-55\,^{\circ}$ C to 125 °C. The SN7450 is characterized for operation from 0 °C to 70 °C.

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for J and N packages.



2Y ☐ 6

GND 17

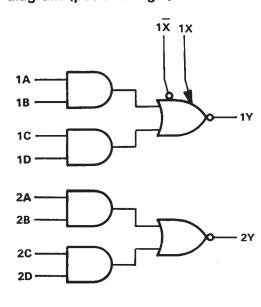
SN5450 . . . W PACKAGE (TOP VIEW)

9 1 C

8 1Y

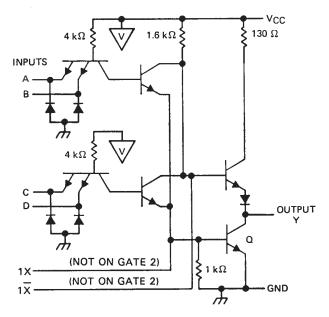
1X □	1 U 14] 1D
1X□:	2 13]1C
1AQ	3 12] 1Y
vcc□ʻ	4 11	GND
18 📮 :	5 10] 2Y
2A 🗆	6 9] 2D
2B[7 8] 2C

logic diagram (positive logic)





schematic (each AND-OR-INVERT gate)



Resistor values shown are nominal. If expander is not used, leave X and \overline{X} open.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	
Input voltage	5.5 V
Operating free-air temperature range:	SN545055°C to 125°C
Operating free an temperature range.	SN7450 0°C to 70°C
	65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



SN5450, SN7450 **DUAL 2-WIDE 2-INPUT AND-OR-INVERT GATES (ONE GATE EXPANDABLE)**

SDLS112 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

			SN5450		SN7450			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ЮН	High-level output current			- 0.4			- 0.4	mA
loL	Low-level output current			16			16	mΑ
TA	Operating free-air temperature	– 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS†				SN5450			SN7450			
PARAMETER	TES	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT			
VIK	V _{CC} = MIN,	I ₁ = - 12 mA				1.5			1.5	V	
Voн	V _{CC} = MIN,	V _{IL} = 0.8 V,	I _{OH} = - 0.4 mA	2.4	3.4		2.4	3.4		٧	
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 16 mA		0.2	0.4		0.2	0.4	V	
I _f	V _{CC} = MAX,	V _I = 5.5 V				1			1	mA	
Чн	V _{CC} = MAX,	V _{IH} = 2.4 V				40			40	μΑ	
ելը	V _{CC} = MAX,	V _{IL} = 0.4 V				- 1.6			– 1.6	mA	
loss	V _{CC} = MAX			- 20		- 55	- 18		– 55	mA	
ГССН	V _{CC} = MAX,	V ₁ = 0 V			4	8		4	8	mA	
¹ CCL	V _{CC} = MAX,	See Note 2			7.4	14		7.4	14	mA	
ı⊼·¶	$V\overline{\chi}\chi = 0.4 V$,	I _{OL} = 16 mA				- 2.9			- 3.1	mA	
.	$I_X + I_{\overline{X}} = 0.41 \text{ mA},$	$R\overline{\chi}\chi = 0$,	I _{OL} = 16 mA			1.1				l v	
V _{BE(Q)} ¶	$1_X + 1_{\overline{X}} = 0.62 \text{ mA},$	$R\overline{\chi}\chi = 0$,	I _{OL} = 16 mA						1		
v ¶	I _X = 0.15 mA,	$I\overline{\chi} = -0.15 \mathrm{mA}$	$I_{OH} = -0.4 \text{ mA}$	2.4	3.4					V	
∨ _{OH} ¶	$I_X = 0.27 \text{ mA},$	$I\overline{\chi} = -0.27 \text{ mA},$	I _{OH} = - 0.4 mA				2.4	3.4		<u> </u>	
v _{OL} ¶	$I_X + I_{\overline{X}} = 0.3 \text{ mA},$	$R\overline{\chi}\chi = 138 \Omega$,	I _{OL} = 16 mA		0.2	0.4				V	
	$I_X + I_{\overline{X}} = 0.43 \text{ mA},$	$R\overline{\chi}_X = 130 \Omega$,	I _{OL} = 16 mA					0.2	0.4		

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
tPLH			$R_L = 400 \Omega$, $C_L = 15 pF$		13	22	ns
tPHL	Any	Y	Expander pins open		8	15	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ} \text{C}$.

[§] Not more than one output should be shorted at a time.

[¶] Using expander inputs, V_{CC} = MIN, T_A = MIN, except typical values. NOTE 2: All inputs of one AND gate at 4.5 V, all others at GND.





www.ti.com 25-Jan-2012

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
JM38510/00501BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/00501BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/00501BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN5450J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN5450J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN7450N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN7450N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SNJ5450J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ5450J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ5450W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SNJ5450W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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25-Jan-2012

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OTHER QUALIFIED VERSIONS OF SN5450, SN7450:

Catalog: SN7450

Military: SN5450

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



NOTES:

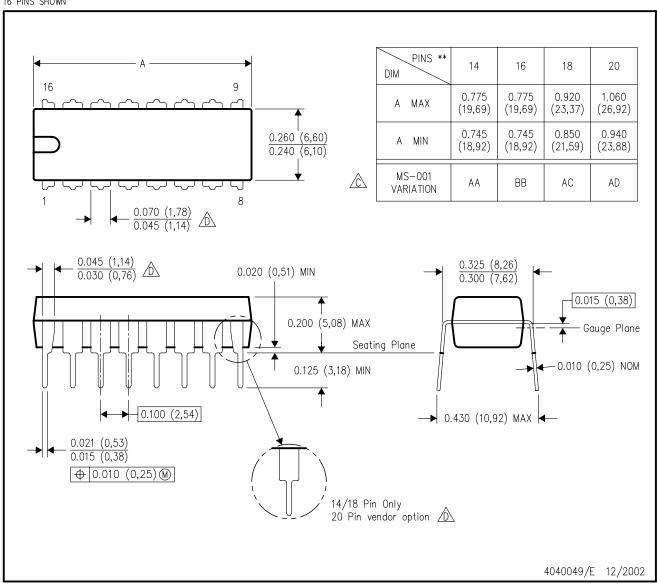
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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